# Errata

## DA14531 Errata

### CE0001

## Abstract

The document contains the known errata for the DA14531 along with recommended workarounds.

<table>
<thead>
<tr>
<th>Product</th>
<th>DA14531</th>
</tr>
</thead>
<tbody>
<tr>
<td>Silicon Revision</td>
<td>0xAE / 0xAF</td>
</tr>
<tr>
<td></td>
<td>(Register CHIP_REVISION_REG, CHIP_TEST1_REG and CHIP_TEST2_REG)</td>
</tr>
<tr>
<td>Datasheet Reference</td>
<td>DA14531_datasheet_2v1.pdf</td>
</tr>
<tr>
<td>Package(s)</td>
<td>WLCSP 17 balls, 1.7x2.05, 0.5 mm pitch</td>
</tr>
<tr>
<td></td>
<td>FCGQFN 24 pins, 2.2x3, 0.4 mm pitch</td>
</tr>
<tr>
<td>Issue Date</td>
<td>1-Nov-2019</td>
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1 Terms and Definitions

GPADC  General Purpose Analog to Digital Converter
RFIO   Radio Frequency Input Output
LO     Local Oscillator
TX     Transmitter

2 Identifying the Silicon Revision

A readback of registers CHIP_REVISION_REG, CHIP_TEST1_REG and CHIP_TEST2_REG will give the device revision information.

3 Workarounds

For the cases where complex software workarounds are recommended in form of concept description, please refer to the special section of the SDK release notes that explains which items are addressed and how.

4 Errata Summary

Table 1: Errata Summary

<table>
<thead>
<tr>
<th>Bug/Enhancement</th>
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</thead>
<tbody>
<tr>
<td>312</td>
</tr>
<tr>
<td>LO spurs and TX harmonics at RFIO pin</td>
</tr>
<tr>
<td>314</td>
</tr>
<tr>
<td>System in boost is stuck at boot if Vbat_high load &gt; 50 uA load</td>
</tr>
<tr>
<td>306</td>
</tr>
<tr>
<td>Small input leakage current when xtal32k_m (P0_4) is high</td>
</tr>
</tbody>
</table>
5 Errata Details

5.1 LO spurs and TX harmonics at RFIO pin

5.1.1 Effect
RX spurs and TX harmonics at the RFIO pin. FCC/ETSI/Asian regulations are violated.

5.1.2 Conditions
Always.

5.1.3 Technical Description
- RX mode: LO spur (@ 4.8GHz)
- TX mode: harmonics might need filtering depending on application and antenna
- Root cause: Parasitic coupling path on the chip towards the output

5.1.4 Workaround
An external CLC (C=1.8pF, L=3.3nH) filter network to be used at RFIOp pin. For details please refer to the Application Note AN-B-073.

5.2 System in boost is stuck at boot if Vbat_high load > 50 uA load

5.2.1 Effect
DA14531 is not booting in the boost configuration when there is a load >50uA present on the VBAT_HIGH rail. The system is then kept in the HW power up state machine.

5.2.2 Conditions
For a load >50uA present on the VBAT_HIGH rail during the initial booting.

5.2.3 Technical Description
In boost mode VBAT_HIGH is charged from VBAT_LOW via a resistive switch until a comparator triggers (VBAT_HIGH > VBAT_LOW - 50mV). Upon this threshold reached, the HW power up state machine will be allowed to continue. When there is a too large resistive load (>50uA DC) on VBAT_HIGH this comparator will never trigger and the system remains stuck in the HW power up state machine.

5.2.4 Workaround
- Avoid a load more than 50uA during booting/powerup phase.
- If an external (SPI flash or I2C EEPROM) should be supplied by the boost DCDC then use a GPIO as a supply source to allow for zero lead at VBAT_HIGH during boot.

5.3 Small input leakage current when xtal32k_m (P0_4 pin) is high

5.3.1 Effect
Pulling pin xtal32k_m high when the oscillator is disabled, results in a small leakage current into this pin (5 to 10nA at 25°C) affecting hibernation current of the application.
5.3.2 Conditions
When the pin is pulled up (high).

5.3.3 Technical Description
Pads can be pulled up during hibernation. This means that the inputs of the xtal32k oscillator will be high while the oscillator is disabled. Backdrive protection is implemented to avoid leakage, however the backdrive transistors are Native NMOS devices with higher channel leakage.

This means that channel leakage of the NMOST will flow into this bulk causing a slight input current on P0_4 (~5 to 10nA at 25C).

The other xtal32k pin (P0_3) does not suffer from this problem since the clamp has been implemented with long channel NMOSTs.

5.3.4 Workaround
None.
# Revision History

<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Description</th>
</tr>
</thead>
<tbody>
<tr>
<td>1.0</td>
<td>1-Nov-2019</td>
<td>Code C version</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Updated issues table with numbers</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Various corrections</td>
</tr>
<tr>
<td>0.1</td>
<td>11-Jul-2019</td>
<td>Clarifications, description improvements</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Errata in ES2 version</td>
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Status Definitions

<table>
<thead>
<tr>
<th>Status</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>DRAFT</td>
<td>The content of this document is under review and subject to formal approval, which may result in modifications or additions.</td>
</tr>
<tr>
<td>APPROVED or unmarked</td>
<td>The content of this document has been approved for publication.</td>
</tr>
</tbody>
</table>

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